



INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(Use as many sheets as necessary)</i>	<i>Complete if Known</i>	
	Application Number	09/989,736
	Filing Date	November 19, 2001
	First Named Inventor	Peleg, Alexander
	Group Art Unit	2193
	Examiner Name	Mai, Tan
Sheet 1 of 1		Attorney Docket No: 42390P2445C3

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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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EXAMINER

/Tan Mai/

DATE CONSIDERED

05/15/2007